



Evyap Sabun Malaysia Sdn Bhd

Evyap Oleo O 1618 Plus

Distilled Fatty Acid C1618

Product Data Sheet

CAS No. 67701-08-0

EINECS No. 266-932-7

Parameter	Unit	Specification
Appearance at 40 Deg. C	-	Clear liquid, free of foreign matter
Colour, Lovibond, Max	In 5, ¼" Cell	Y=10.0; R=1.0
Acid Value	mg KOH/Gm	198 - 213
Sap. Value	mg KOH/Gm	199 - 214
Iodine Value	Gm I ₂ / 100 Gm	57.0 Min

Fatty Acid Composition	Unit	Specification
C 14 & Below	% by GC	3.0 Max
C 16	% by GC	35.0 Max
C 18:0	% by GC	4.0 – 12.0
C 18:1	% by GC	50.0 Min
C 18:2	% by GC	6.0 – 11.0

The above chart indicates typical available specifications. Customised specifications are also available.

APPLICATIONS

Preparation of food ingredients, cosmetics and personal care products, surfactant manufacture, soap noodles, industrial application like candle, paper manufacturing, coatings, PVC Stabilizer and fabric softener.

PACKING

Available in standard 180kg MS/HDPE drums, road tankers or bulk ISO container loads. Customised packing size can be made available upon request.

BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

Evyap Sabun Malaysia Sdn Bhd

PL0 70, Jalan Nibong 4, Tanjung Langsat Industrial Complex, 81700 Pasir Gudang, Johor Darul Takzim, Malaysia.

Telephone: +607 252 7000; Fax: +607 252 0777,

Website: www.evyapoleo.com

E-mail: ESMSales@evyap.com.tr

Information contained in this publication is true and accurate to the best of our knowledge. The nominal values stated here are obtained using laboratory test specimens. Evyap Sabun Malaysia and its affiliated companies do not accept any liability whatsoever arising from the use of this information or the use, application or processing of any product described herein. No information contained in this publication can be considered as a suggestion to infringe patents. The company disclaims any liability that may be claimed for infringement or alleged infringement of patents